

Preliminary Amendment

Applicant: Wolfgang Hetzel et al.

Serial No.: Unknown

(Priority Application No. DE 103 50 239.4)

(International Application No. PCT/DE2004/002374)

Filed: Herewith

(Priority Date: October 27, 2003)

(International Filing Date: October 25, 2004)

Docket No.: I431.156.101/FIN546PCT/US

Title: SEMICONDUCTOR DEVICE WITH PLASTIC PACKAGE MOLDING COMPOUND,
SEMICONDUCTOR CHIP AND LEADFRAME AND METHOD FOR PRODUCING THE SAME

IN THE SPECIFICATION

Please insert the following paragraph beginning at page 1, line 5, of the substitute specification with the following paragraph:

Cross Reference to Related Application

This Utility Patent Application claims the benefit of the filing date of German Application No. DE 103 50 239.4, October 27, 2003, and International Application No. PCT/DE2004/002374, filed October 25, 2004, both of which are herein incorporated by reference.